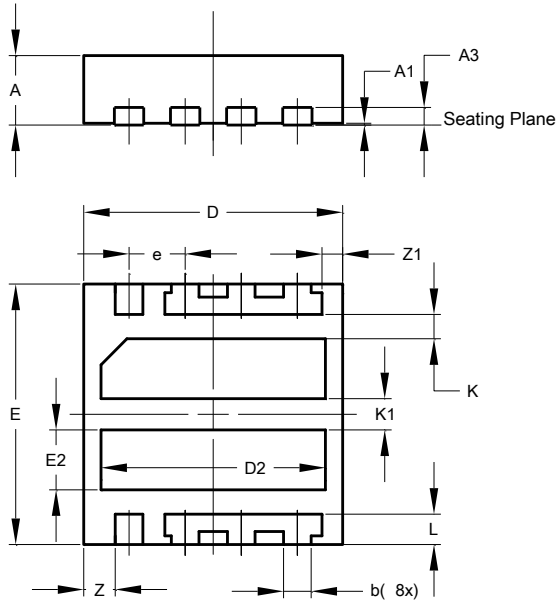


Package Outline Dimensions

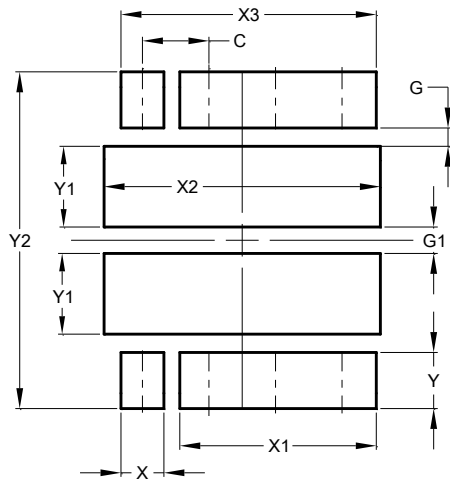
V-DFN3030-8 Type H



V-DFN3030-8 (Type H)			
Dim	Min	Max	Typ
A	0.75	0.85	0.80
A1	0	0.05	0.02
A3	0.203 BSC		
b	0.27	0.37	0.32
D	2.95	3.05	3.00
D2	2.50	2.70	2.60
e	0.65 BSC		
E	2.95	3.05	3.00
E2	0.59	0.79	0.69
L	0.30	0.40	0.35
K	0.28 BSC		
K1	0.36 BSC		
Z	0.365 BSC		
Z1	0.24 BSC		
All Dimensions in mm			

Suggested Pad Layout

V-DFN3030-8 Type H



Dimensions	Value (in mm)
C	0.650
G	0.180
G1	0.260
X	0.420
X1	1.920
X2	2.700
X3	2.495
Y	0.550
Y1	0.790
Y2	3.300

ALL DIMENSIONS ARE NOMINAL VALUES SHOWN IN MILLIMETERS

Note: The suggested land pattern dimensions have been provided for reference only, as actual pad layouts may vary depending on application. These numbers may be modified based on user equipment capability or fabrication criteria. A more robust pattern may be desired for wave soldering and is calculated by adding 0.2 mm to the 'Z' dimension. For further information, please reference document IPC-7351A, Naming Convention for Standard SMT Land Patterns, and for International grid details, please see document IEC, Publication 97.